

TEST SOCKETS, TEST SYSTEMS, AND METHODS FOR TESTING  
MICROFEATURE DEVICES

ABSTRACT OF THE DISCLOSURE

Test sockets, test systems, and methods for testing microfeature devices with a substrate and a plurality of conductive interconnect elements projecting from the substrate. In one embodiment, a test socket includes a support surface and a plurality of apertures in the support surface corresponding to at least some of the interconnect elements of the microfeature device. The individual apertures extend through the test socket and are sized to receive a portion of one of the interconnect elements so that the substrate is spaced apart from the support surface when the microfeature device is received in the test socket. In one aspect of this embodiment, the individual apertures have a cross-sectional dimension less than a cross-sectional dimension of the interconnect elements so that the apertures receive only a portion of the corresponding interconnect element.